

## Super-Junction Power Mosfet

### 1. Product Information

#### Features

- Low FOM  $R_{DS(ON)} \times Q_G$
- Fast Switching Capability
- Lead Free Product Is Acquired
- 100% UIS and Isolation Tested

#### Applications

- EV Charger
- Sever/Telecom/PC Power
- AC-DC Power Management
- Solar Inverter

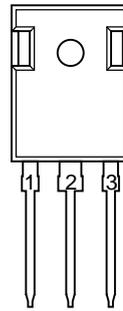
#### Quick reference

- $V_{DS} \cong 600\text{ V}$
- $I_D \leq 100\text{ A}$
- $R_{DS(ON)} \leq 26\text{ m}\Omega @ V_{GS} = 10\text{ V}$  (Type 21  $\text{m}\Omega$ )

#### Pin Description

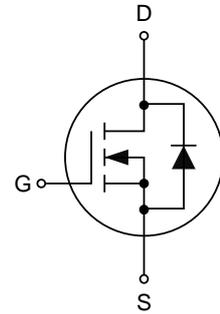
Pin	Description
1	Gate(G)
2	Drain(D)
3	Source(S)

#### Simplified Outline



Top View  
TO-247

#### Symbol



#### Package Marking and Ordering Information

Product Name	Marking	Package	Packaging	Quantity (pcs)
KJC60R026P	KJC60R026P	TO-247	Tube	30

### 2. Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Values	Unit
$V_{DS}$	Drain-Source Voltage	600	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D$	Continuous Drain Current ( $T_C=25^\circ\text{C}$ ) <sup>[1]</sup>	100	A
	Continuous Drain Current ( $T_C=100^\circ\text{C}$ ) <sup>[1]</sup>	62	A
$I_{DM}$	Pulsed Drain Current <sup>[1]</sup>	400	A
$E_{AS}$	Single Pulsed Avalanche Energy	2640	mJ
$P_D$	Power Dissipation <sup>[1]</sup>	621	W
$dv/dt$	Peak Diode Recovery $dv/dt$	5	V/ns
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance, Junction-Ambient <sup>[2]</sup>	35	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction- Case <sup>[2]</sup>	0.2	$^\circ\text{C/W}$

### 3. Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Type	Max	Unit
<b>Static Characteristics</b>						
B <sub>V</sub> DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0 V, I <sub>D</sub> =250 μA	600	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =600 V, V <sub>GS</sub> =0 V, T <sub>J</sub> =25°C	-	-	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±30 V, V <sub>DS</sub> =0 V	-	-	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =2 mA	3.0	-	4.5	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10 V, I <sub>D</sub> =40 A	-	20	26	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50 V, V <sub>GS</sub> =0 V, F=1 MHz	-	9316	-	pF
C <sub>oss</sub>	Output Capacitance		-	323	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	7.6	-	pF
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =300 V, I <sub>D</sub> =50 A, R <sub>G</sub> =25 Ω, V <sub>GS</sub> =10V	-	193	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	97	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	460	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	111	-	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =480 V, I <sub>D</sub> =50 A, V <sub>GS</sub> =10 V	-	295	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	58	-	nC
Q <sub>gd</sub>	Gate-Drain Charge		-	76	-	nC
<b>Source-Drain Diode Characteristics</b>						
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>F</sub> =50 A	-	-	1.4	V
I <sub>S</sub>	Diode Continuous Forward Current		-	-	100	A
I <sub>SM</sub>	Maximum Pulsed Body-Diode Forward Current		-	-	400	A
Q <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> =0 V, I <sub>F</sub> =50 A, di/dt=100 A/μs	-	212	-	μC
T <sub>rr</sub>	Reverse Recovery Charge		-	2.5	-	ns

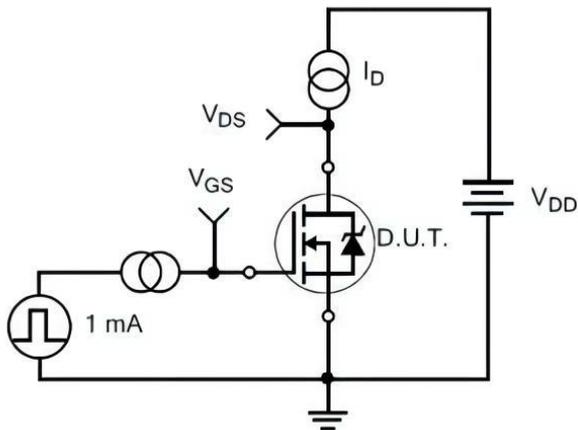
Notes:

- Limited by maximum junction temperature
- Mount on minimum PCB layout.

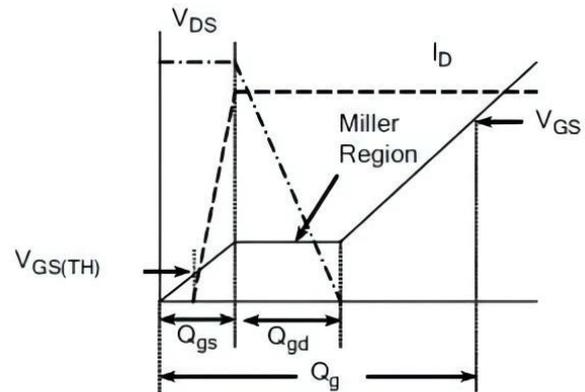
## 4. Test Circuits and Waveforms ( $T_J=25^\circ\text{C}$ )

**Table 1. Gate Charge Test Circuit and Waveforms**

Gate Charge Test Circuit

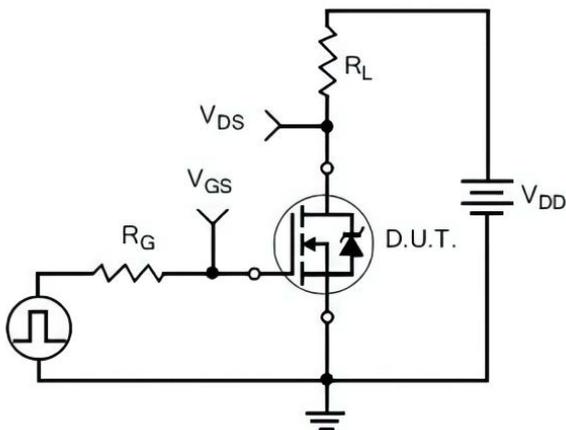


Gate Charge Waveforms

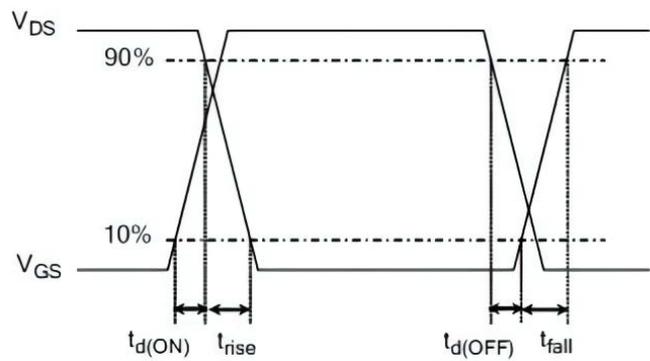


**Table 2. Resistive Switching Test Circuit and Waveforms**

Resistive Switching Test Circuit

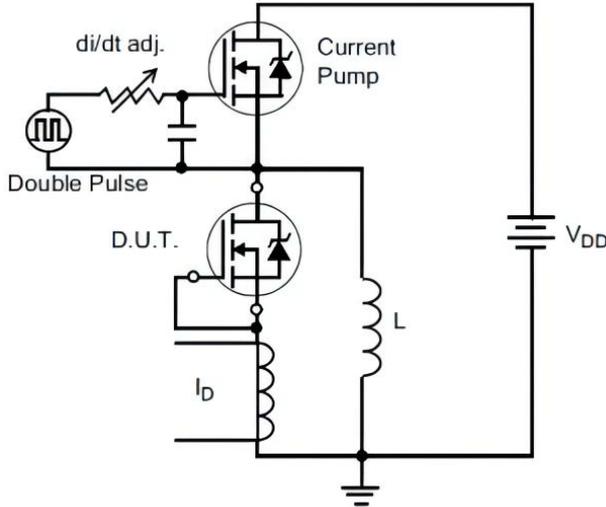


Resistive Switching Waveforms

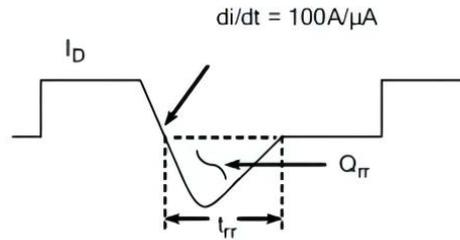


**Table 3. Diode Recovery Test Circuit and Waveforms**

Diode Recovery Test Circuit

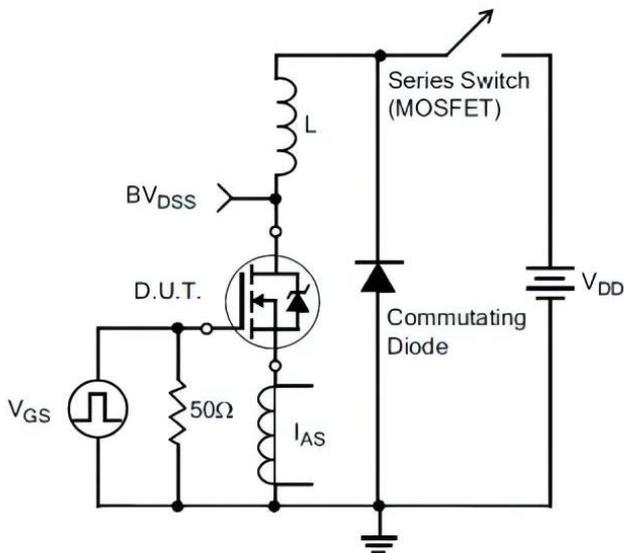


Diode Recovery Waveforms

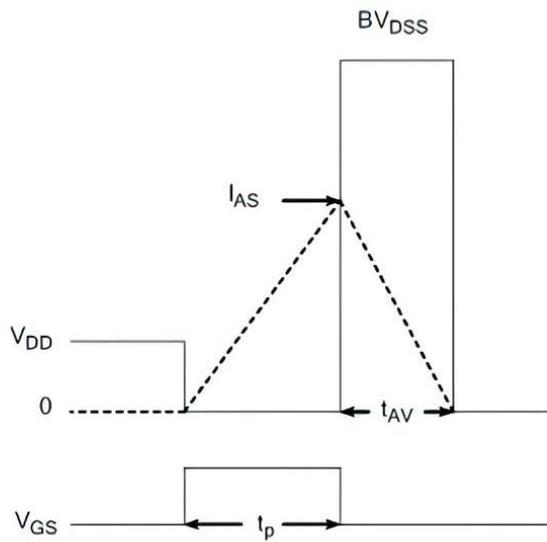


**Table 4. Unclamped inductive Switching (UIS) Test Circuit and Waveforms**

Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms



$$E_{AS} = \frac{I_{AS}^2 L}{2}$$

## 5. Electrical Characteristics

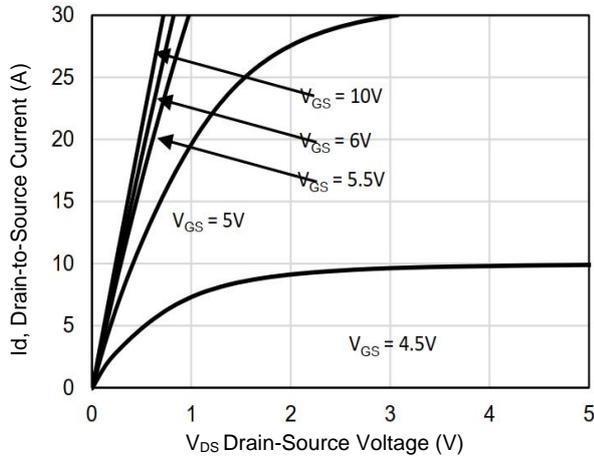


Figure 1. Typical Output Characteristics

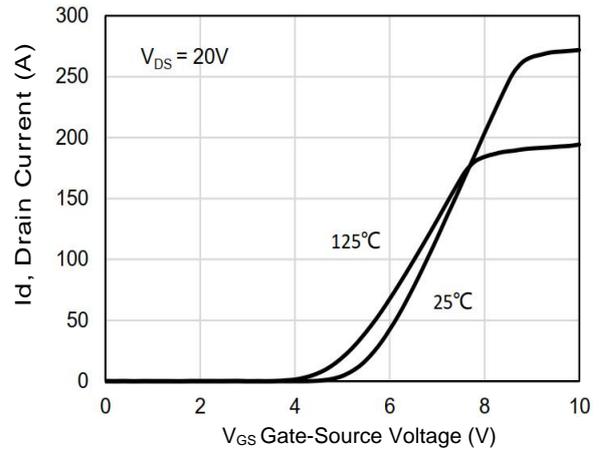


Figure 2. Typical Transfer Characteristics

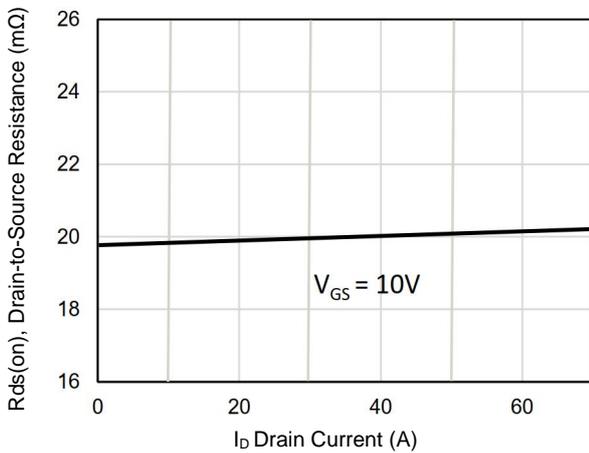


Figure 3. On-Resistance versus Drain Current

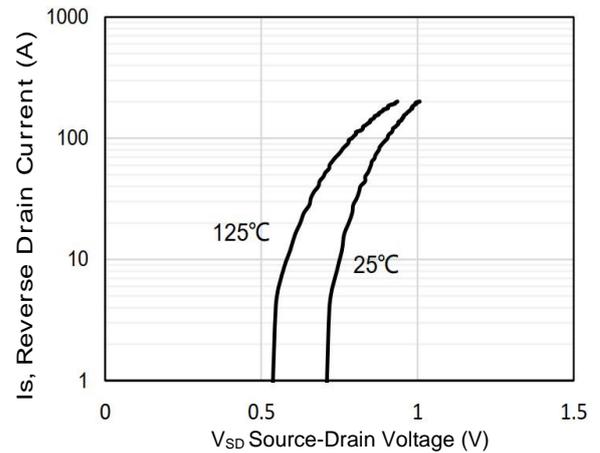


Figure 4. Diode forward voltage versus Current

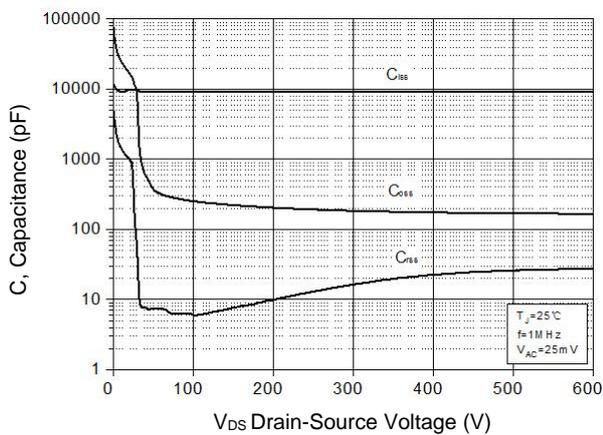


Figure 5. Typical Capacitance versus  $V_{DS}$

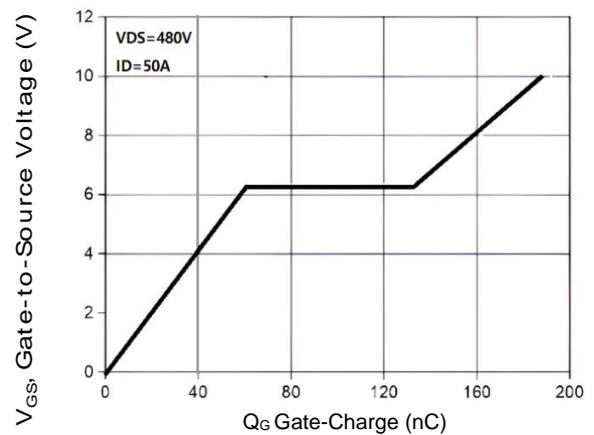


Figure 6. Typical Gate Charge versus  $V_{GS}$

## 5. Electrical Characteristics (cont.)

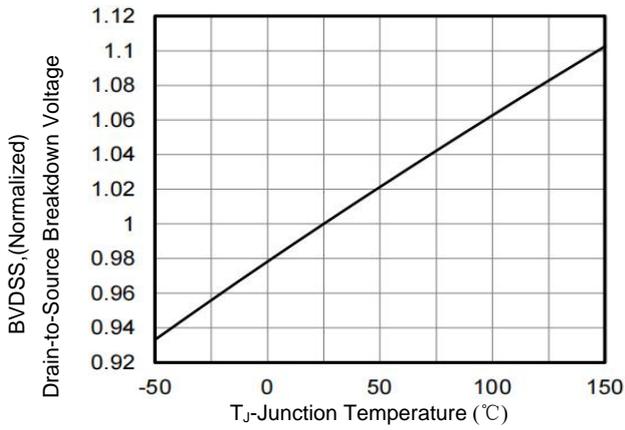


Figure 7.  $BV_{DSS}$  Variation with Temperature

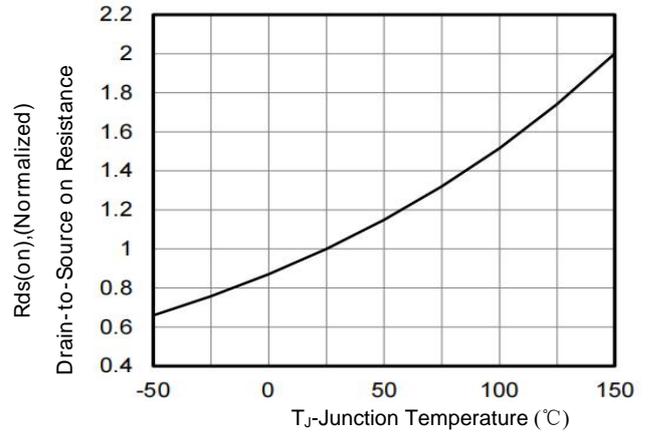


Figure 8. On-Resistance Variation with Temperature

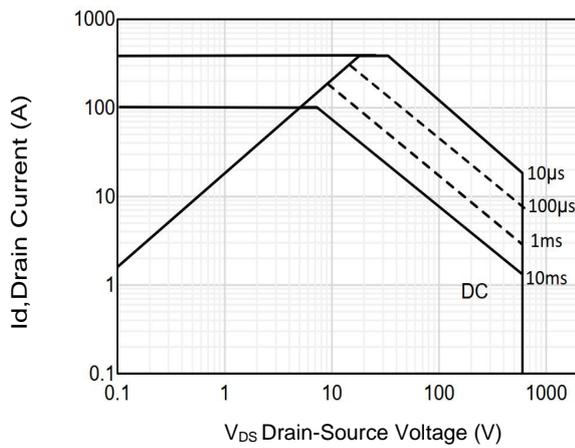


Figure 9. Maximum Safe Operating Area

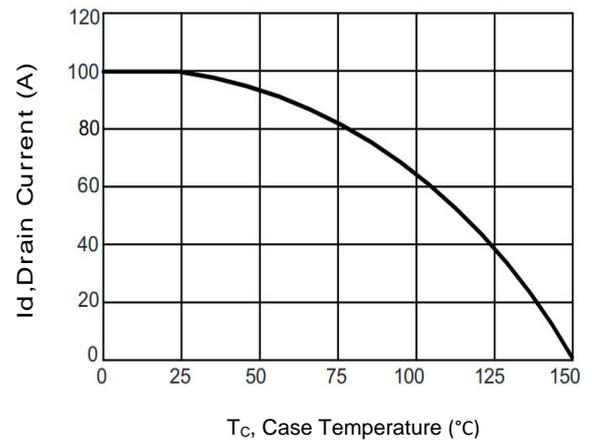
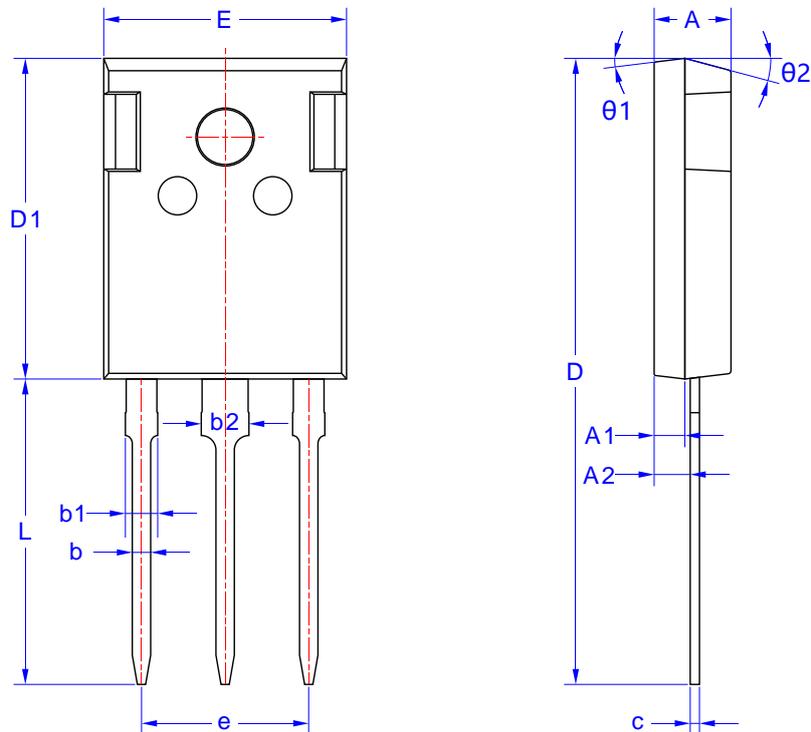


Figure 10. Maximum Continuous Drain Current versus Case Temperature

## 6. Package Mechanical Data

### TO-247 Package



Symbol	Dimensions in Millimeters		
	MIN.	NOM.	MAX.
A	4.90	5.00	5.10
A1	1.90	2.00	2.10
A2	2.25	2.35	2.45
b		1.20	
b1		2.10	
b2		3.10	
c		0.60	
D	40.00	41.00	42.00
D1	20.80	21.00	21.20
E	15.60	15.80	16.00
e		10.88	
L	19.80	20.00	20.20
θ1		7°	
θ2		15°	